

protruded from the second material, wherein; a laser beam of which wavelength has the light absorption coefficient of the first material being higher than the light absorption coefficient of the second material, is irradiated onto an boundary area between the first material and an end of the second material.

2. The method of laser processing claimed in claim 1, wherein the laser beam is defocused and condensed spot of the defocused light beam is irradiated onto both the first material and the end of the second material.
3. The method of laser processing claimed in claim 1 or 2, wherein; the laser beam, which is a femto second laser beam, is irradiated onto a boundary area between the first material and the end of the second material.
4. The method of laser processing claimed in claim 1 or 2, wherein; a plurality of laser beams having a different wavelength respectively are irradiated onto a boundary area between the first material and the end of the second material.
5. The method of laser processing claimed in any of claims 1 to 4, wherein; a material, which has the light absorption coefficient being higher than the light absorption coefficient of the second material, is coated over a processed portion in the first material.
6. The method of laser processing claimed in any of claims 1 to 4, wherein; a plurality of minute uneven portions are formed on the surface of a processed portion in the first material.
7. The method of laser processing claimed in any of claims 1 to 6, wherein; the direction of irradiating the laser beam to the laminated member is adjustable.
8. The method of laser processing claimed in any of claims 1 to 7, wherein; an airflow blowing materials scattered by the processing toward the outside of the laminated member is supplied.
9. The method of laser processing claimed in any of claims 1 to 8, wherein; the laser beam is irradiated onto the laminated member in a vacuum.
10. The method of laser processing claimed in any of claims 1 to 9, wherein; the laser beam is irradiated onto the laminated member, scanning the laser by using a galvanic mirror.
11. The method of laser processing claimed in any of claims 1 to 10, wherein; the laser beam is made to be branched off and the branched plurality of beams are irradiated onto the laminated member at the same

time.

12. The method of laser processing claimed in any of claims 1 to 10, wherein; a portion to be processed in the laminated member is shot by a camera and an image thereof is processed such that the position to be irradiated with a laser beam is determined thereby.

13. The method of laser processing claimed in any of claims 1 to 12, wherein; the first material is a metal, and the second material is silicon.

14. The method of laser processing claimed in any of claims 1 to 12, wherein; the first material is silicon, and the second material is a glass.

15. The method of laser processing claimed in any of claims 1 to 12, wherein; the second material is a cavity substrate for a head of ejecting a droplet provided with a concave portion functioning as a reservoir for a liquid material and the first material is a multi-layered film of which layers are deposited on the bottom of the reservoir of the cavity substrate.

16. A head for ejecting a droplet comprising a reservoir for a liquid material formed by the method claimed in claim 15.

17. A method of laser processing for processing a boundary area composed of materials having different light absorption coefficients, wherein;

a laser beam of which wavelength has the light absorption coefficient of a second material being higher than the light absorption coefficient of a first material, is irradiated onto the boundary area.

18. A method of laser processing comprising;

a step of forming a boundary area with a first material having first light absorption property with respect to a laser beam and a second material having second light absorption property, which is different from the first light absorption property ; and

a step of processing one of the first material and/or the second material by irradiating the laser beam onto the boundary area.